

**WHAT IS CLAIMED IS**

1. An inspection apparatus for inspecting a plurality of semiconductor integrated circuits mounted on a base board, the apparatus comprising:

5       aplurality of relay pins electrically connected to a wiring pattern laid on the base board;

          sockets provided on the base board, each housing a semiconductor integrated circuit;

          exchange boards, each electrically connecting socket  
10    terminals of a socket to a specific relay pin; and

          spacers interposed between each of the exchange boards and the base board.

2. The inspection apparatus according to claim 1, wherein  
15   the exchange board is a film-like sheet board, and a reinforcement plate for reinforcing the sheet-like board is provided between the sheet-like board and the spacers.

3. The inspection apparatus according to claim 1, wherein  
20   the exchange board is provided with a pin socket for holding the relay pins, and the relay pins are removably attached to the exchange board.

4. The inspection apparatus according to claim 1, wherein  
25   the base board has a pin socket for holding the relay pins, and the exchange board is removable from the base board together with the relay pins.

5. The inspection apparatus according to claim 1, wherein  
30   a circuit element or a pattern for receiving a circuit element is formed in an area on the base board, the area opposing the exchange board.

6. The inspection apparatus according to claim 1, wherein a circuit element or a pattern for receiving a circuit element is formed in an area on the exchange board, the area opposing the base board.

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7. An inspection apparatus for inspecting a plurality of semiconductor integrated circuits mounted on a base board, wherein the base board comprises:

aplurality of connection terminals electrically connected  
10 to terminals of an inspection main unit;

a plurality of wiring patterns connected to terminals of a semiconductor integrated circuit; and

a junction unit for changing the state of a junction formed between the connection terminals and the wiring pattern.

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8. The inspection apparatus according to claim 7, wherein the junction unit includes a pin socket for connecting the wiring pattern to the connection terminals when a pin is inserted into the pin socket, and the pin socket is interposed between each  
20 of a plurality of wiring patterns and a single connection terminal and/or between each of a plurality of connection terminals and a single wiring pattern.

9. The inspection apparatus according to claim 7, wherein  
25 the junction unit includes an element mount pattern for connecting the wiring pattern to the connection terminals when a short-circuit element is mounted on the element mount pattern, and the element mount pattern is provided between each of a plurality of wiring patterns and a single connection terminal  
30 and/or between each of a plurality of connection terminals and a single wiring pattern.

10. The inspection apparatus according to claim 7, wherein  
the junction unit includes at least one of a dip switch for switching  
a junction between each of a plurality of wiring patterns and  
a single connection terminal, and a dip switch for switching a  
5 junction between a plurality of connection terminals and a single  
wiring pattern.

11. An inspection method for inspecting a semiconductor  
integrated circuit using the inspection apparatus according to  
10 claim 1.